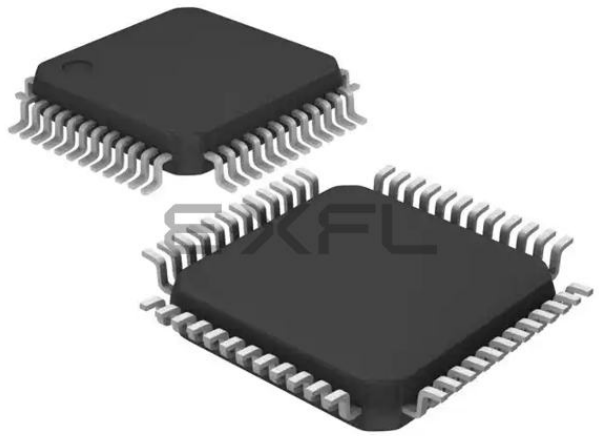

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Details	
Product Status	Active
Core Processor	S12Z
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SCI, SPI, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	5.5V ~ 18V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12zvl16f0vlf

1.7.2.24 BDC and Debug Signals

1.7.2.24.1 BKGD — Background Debug signal

The BKGD signal is used as a pseudo-open-drain signal for the background debug communication. The BKGD signal has an internal pull-up device.

1.7.2.24.2 DBGEEV — External Event Input

This signal is the DBG external event input. It is input only. Within the DBG module, it allows an external event to force a state sequencer transition. A falling edge at the external event signal constitutes an event. Rising edges have no effect. The maximum frequency of events is half the internal core bus frequency.

1.7.2.25 CAN0 Signals

1.7.2.25.1 RXCAN0 Signal

This signal is associated with the receive functionality of the scalable controller area network controller (MSCAN0).

1.7.2.25.2 TXCAN0 Signal

This signal is associated with the transmit functionality of the scalable controller area network controller (MSCAN0).

1.7.2.26 LIN Physical Layer Signals

1.7.2.26.1 LIN

This pad is connected to the single-wire LIN data bus.

1.7.2.26.2 LPTXD

This is the LIN physical layer transmitter input signal.

1.7.2.26.3 LPRXD

This is the LIN physical layer receiver output signal.

1.7.2.26.4 LPDR1

This is the LIN LP0DR1 register bit, visible at the designated pin for debug purposes.

1.7.2.27 BCTL

BCTL is the ballast connection for the on chip voltage regulator. It provides the base current of an external PNP transistor of the VDDX and VDDA supplies.

1.7.3 Power Supply Pins

The power and ground pins are described below. Because fast signal transitions place high, short-duration current demands on the power supply, use bypass capacitors with high-frequency characteristics and place them as close to the MCU as possible.

NOTE

All ground pins must be connected together in the application.

1.7.3.1 VDDX, VSSX1, VSSX2 — Digital I/O Power and Ground Pins

VDDX is the voltage regulator output to supply the digital I/O drivers.It supplies the VDDX domain pads. The VSSX1and VSSX2 pin are the ground pin for the digital I/O drivers.

Bypass requirements on VDDX, VSSX2 depend on how heavily the MCU pins are loaded.

1.7.3.2 VDDA, VSSA — Power Supply Pins for ADC

These are the power supply and ground pins for the analog-to-digital converter and the voltage regulator. These pins must be externally connected to the voltage regulator (VDDX, VSSX). A separate bypass capacitor for the ADC supply is recommended.

1.7.3.3 VSS — Core Ground Pin

The voltage supply of nominally 1.8V is generated by the internal voltage regulator. The return current path is through the VSS pin.

1.7.3.4 LGND — LINPHY Ground Pin

LGND is the ground pin for the LIN physical layer LINPHY. This pin must be connected to board ground, even if the LINPHY is not used.

1.7.3.5 VSUP — Voltage Supply Pin for Voltage Regulator

VSUP is the 12V/18V supply voltage pin for the on chip voltage regulator. This is the voltage supply input from which the voltage regulator generates the on chip voltage supplies. It must be protected externally against a reverse battery connection.

1.8 Device Pinouts

MC9S12ZVL-Family is available in 48-pin package and 32-pin package. Signals in parentheses in Figure 1-3 to Figure 1-5 denote alternative module routing options.

The exposed pad must be connected to a grounded contact pad on the PCB. The exposed pad has an electrical connection within the package to VSSFLAG (VSSX die connection).

1.13 Module device level dependencies

1.13.1 COP Configuration

The COP time-out rate bits CR[2:0] and the WCOP bit in the CPMUCOP register are loaded from the Flash configuration field byte at global address 0xFF_FE0E during the reset sequence. See Table 1-13 and Table 1-14 for coding.

Table 1-13. Initial COP Rate Configuration

NV[2:0] in FOPT Register	CR[2:0] in COPCTL Register
000	111
001	110
010	101
011	100
100	011
101	010
110	001
111	000

Table 1-14. Initial WCOP Configuration

NV[3] in FOPT Register	WCOP in COPCTL Register
1	0
0	1

1.13.2 BDC Command Restriction

The BDC command READ_DBGTB returns 0x00 on this device because the DBG module does not feature a trace buffer.

4.1.1 Glossary

Table 4-2. Glossary Of Terms

Term	Definition
MCU	Microcontroller Unit
CPU	S12Z Central Processing Unit
BDC	S12Z Background Debug Controller
ADC	Analog-to-Digital Converter
unmapped address range	Address space that is not assigned to a memory
reserved address range	Address space that is reserved for future use cases
illegal access	Memory access, that is not supported or prohibited by the S12ZDBG, e.g. a data store to NVM
access violation	Either an illegal access or an uncorrectable ECC error
byte	8-bit data
word	16-bit data

4.1.2 Overview

The S12ZDBG provides access to on-chip memories and peripherals for the S12ZCPU, the S12ZBDC, and the ADC. It arbitrates memory accesses and determines all of the MCU memory maps. Furthermore, the S12ZDBG is responsible for selecting the MCUs functional mode.

4.1.3 Features

- S12ZDBG mode operation control
- Memory mapping for S12ZCPU, S12ZBDC, and ADC
  - — Maps peripherals and memories into a 16 MByte address space for the S12ZCPU, the S12ZBDC, and the ADC
  - — Handles simultaneous accesses to different on-chip resources (NVM, RAM, and peripherals)
- Access violation detection and logging
  - — Triggers S12ZCPU machine exceptions upon detection of illegal memory accesses and uncorrectable ECC errors
  - — Logs the state of the S12ZCPU and the cause of the access error

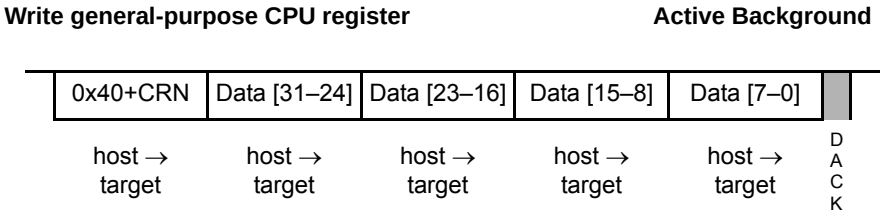
4.1.4 Modes of Operation

4.1.4.1 Chip configuration modes

The S12ZDBG determines the chip configuration mode of the device. It captures the state of the MODC pin at reset and provides the ability to switch from special-single chip mode to normal single chip-mode.

The hardware forces low-order address bits to zero longword accesses to ensure these accesses are on 0-modulo-size alignments. Byte alignment details are described in Section 5.4.5.2, “BDC Access Of Device Memory Mapped Resources”.

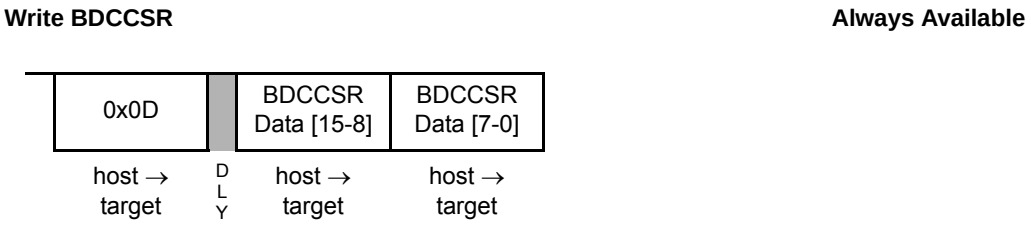
5.4.4.17 WRITE_Rn



If the device is in active BDM, this command writes the 32-bit operand to the selected CPU general-purpose register. See Section 5.4.5.1, “BDC Access Of CPU Registers for the CRN details. Accesses to CPU registers are always 32-bits wide, regardless of implemented register width. If enabled an ACK pulse is generated after the internal write access has been completed or aborted.

If the device is not in active BDM, this command is rejected as an illegal operation, the ILLCMD bit is set and no operation is performed.

5.4.4.18 WRITE_BDCCSR



16-bit write to the BDCCSR register. No ACK pulse is generated. Writing to this register can be used to configure control bits or clear flag bits. Refer to the register bit descriptions.

5.4.4.19 ERASE_FLASH

Mass erase the internal flash. This command can always be issued. On receiving this command twice in succession, the BDC sets the ERASE bit in BDCCSR and requests a flash mass erase. Any other BDC command following a single ERASE_FLASH initializes the sequence, such that thereafter the ERASE_FLASH must be applied twice in succession to request a mass erase. If 512 BDCSI clock cycles

If the handshake protocol is disabled, the access is always independent of free cycles, whereby BDC has higher priority than CPU. Since at least 2 bytes (command byte + data byte) are transferred over BKGD the maximum intrusiveness is only once every few hundred cycles.

After decoding an internal access command, the BDC then awaits the next internal core clock cycle. The relationship between BDCSI clock and core clock must be considered. If the host retrieves the data immediately, then the BDCSI clock frequency must not be more than 4 times the core clock frequency, in order to guarantee that the BDC gains bus access within 16 the BDCSI cycle DLY period following an access command. If the BDCSI clock frequency is more than 4 times the core clock frequency, then the host must use a suitable delay time before retrieving data (see 5.5.1/5-164). Furthermore, for stretched read accesses to external resources via a device expanded bus (if implemented) the potential extra stretch cycles must be taken into consideration before attempting to obtain read data.

If the access does not succeed before the host starts data retrieval then the NORESP flag is set but the access is not aborted. The NORESP state can be used by the host to recognize an unexpected access conflict due to stretched expanded bus accesses. Although the NORESP bit is set when an access does not succeed before the start of data retrieval, the access may succeed in following bus cycles if the internal access has already been initiated.

5.4.10 Single Stepping

When a STEP1 command is issued to the BDC in active BDM, the CPU executes a single instruction in the user code and returns to active BDM. The STEP1 command can be issued repeatedly to step through the user code one instruction at a time.

If an interrupt is pending when a STEP1 command is issued, the interrupt stacking operation occurs but no user instruction is executed. In this case the stacking counts as one instruction. The device re-enters active BDM with the program counter pointing to the first instruction in the interrupt service routine.

When stepping through the user code, the execution of the user code is done step by step but peripherals are free running. Some peripheral modules include a freeze feature, whereby their clocks are halted when the device enters active BDM. Timer modules typically include the freeze feature. Serial interface modules typically do not include the freeze feature. Hence possible timing relations between CPU code execution and occurrence of events of peripherals no longer exist.

If the handshake protocol is enabled and BDCCIS is set then stepping over the STOP instruction causes the Long-ACK pulse to be generated and the BDCCSR STOP flag to be set. When stop mode is exited due to an interrupt the device enters active BDM and the PC points to the start of the corresponding interrupt service routine. Stepping can be continued.

Stepping over a WAI instruction, the STEP1 command cannot be finished because active BDM cannot be entered after CPU starts to execute the WAI instruction.

Stepping over the WAI instruction causes the BDCCSR WAIT and NORESP flags to be set and, if the handshake protocol is enabled, then the Long-ACK pulse is generated. Then the device enters wait mode, clears the BDMACT bit and awaits an interrupt to leave wait mode. In this time non-intrusive BDC commands are possible, although the STEP1 has actually not finished. When an interrupt occurs the device leaves wait mode, enters active BDM and the PC points to the start of the corresponding interrupt service routine. A further ACK related to stepping over the WAI is not generated.

Table 7-15. SSF[2:0] — State Sequence Flag Bit Encoding

SSF[2:0]	Current State
000	State0 (disarmed)
001	State1
010	State2
011	State3
100	Final State
101,110,111	Reserved

7.3.2.8 Debug Comparator A Control Register (DBGACTL)

Address: 0x0110

	7	6	5	4	3	2	1	0
R	0	NDB	INST	0	RW	RWE	reserved	COMPE
W								
Reset	0	0	0	0	0	0	0	0

= Unimplemented or Reserved

Figure 7-11. Debug Comparator A Control Register

Read: Anytime.

Write: If DBG not armed.

Table 7-16. DBGACTL Field Descriptions

Field	Description
6 NDB	**Not Data Bus** — The NDB bit controls whether the match occurs when the data bus matches the comparator register value or when the data bus differs from the register value. This bit is ignored if the INST bit in the same register is set. 0 Match on data bus equivalence to comparator register contents 1 Match on data bus difference to comparator register contents
5 INST	**Instruction Select** — This bit configures the comparator to compare PC or data access addresses. 0 Comparator compares addresses of data accesses 1 Comparator compares PC address
3 RW	**Read/Write Comparator Value Bit** — The RW bit controls whether read or write is used in compare for the associated comparator. The RW bit is ignored if RWE is clear or INST is set. 0 Write cycle is matched 1 Read cycle is matched
2 RWE	**Read/Write Enable Bit** — The RWE bit controls whether read or write comparison is enabled for the associated comparator. This bit is ignored when INST is set. 0 Read/Write is not used in comparison 1 Read/Write is used in comparison
0 COMPE	**Enable Bit** — Determines if comparator is enabled 0 The comparator is not enabled 1 The comparator is enabled

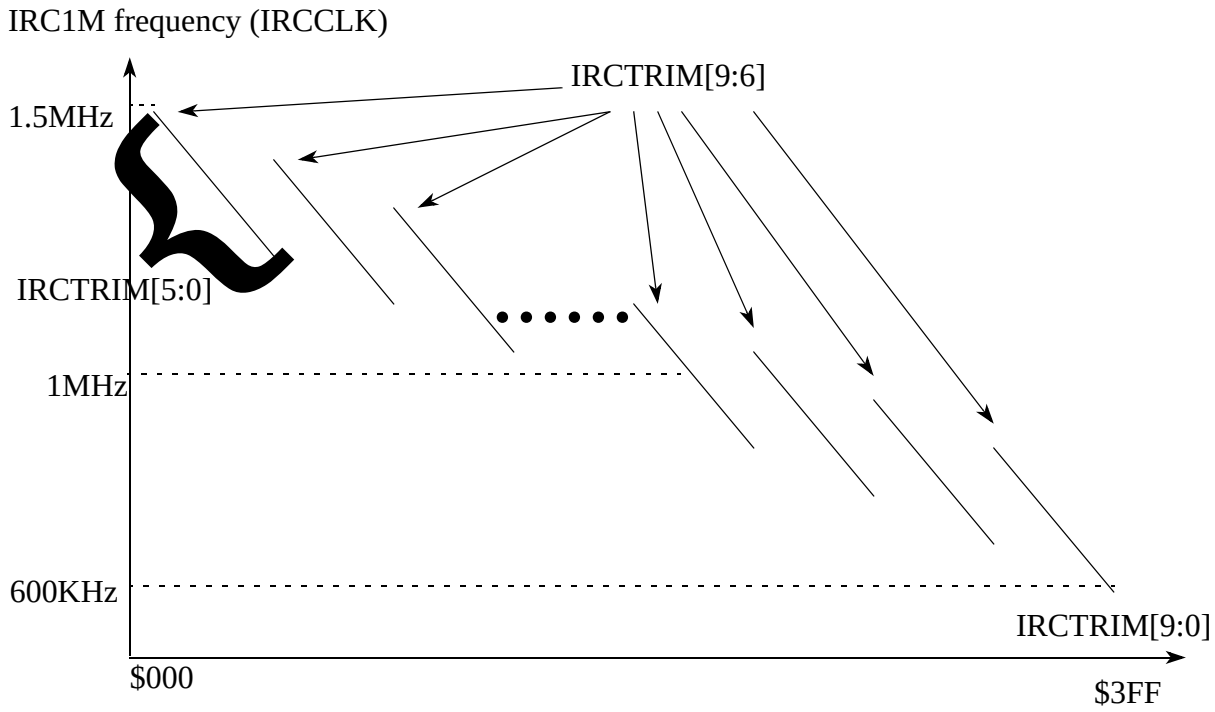


Figure 9-31. IRC1M Frequency Trimming Diagram

Address	Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0024	ADCCROFF0	R	0	CMDRES_OFF0[6:0]						
		W								
0x0025	ADCCROFF1	R	0	CMDRES_OFF1[6:0]						
		W								
0x0026	Reserved	R	0	0	0	0	Reserved			
		W								
0x0027	Reserved	R	Reserved							
		W								
0x0028	Reserved	R	Reserved						0	0
		W								
0x0029	Reserved	R	Reserved	0	Reserved					
		W								
0x002A-0x003F	Reserved	R	0	0	0	0	0	0	0	0
		W								

= Unimplemented or Reserved

Figure 10-3. ADC12B_LBA Register Summary (Sheet 3 of 3)

– *Function:*
Start the first conversion of a conversion sequence which is defined in the active Command Sequence List

– *Requested by:*
- Positive edge of internal interface signal Trigger
- Write Access via data bus to set control bit TRIG

– *When finished:*
This bit is cleared by the ADC when the first conversion of the sequence is beginning to sample

– *Mandatory Requirements:*
- In all ADC conversion flow control modes bit TRIG is only set (Trigger Event executed) if the Trigger Event occurs while no conversion or conversion sequence is ongoing (ADC idle)
- In ADC conversion flow control mode “Restart Mode” with a Restart Event in progress it is not allowed that a Trigger Event occurs before the background command load phase has finished (Restart Event has been executed) else the error flag TRIG_EIF is set
- In ADC conversion flow control mode “Trigger Mode” a Restart Event causes bit TRIG being set automatically. Bit TRIG is set when no conversion or conversion sequence is ongoing (ADC idle) and the RVL done condition is reached by one of the following:
* A “End Of List” command type has been executed
* A Sequence Abort Event is in progress or has been executed
The ADC executes the Restart Event followed by the Trigger Event.
- In ADC conversion flow control mode “Trigger Mode” a Restart Event and a simultaneous Trigger Event via internal interface or data bus causes the TRIG_EIF bit being set and ADC cease operation.

• **Restart Event** (with current active CSL)
Internal Interface Signal: Restart
Corresponding Bit Name: RSTA

– *Function:*
- Go to top of active CSL (clear index register for CSL)
- Load one background command register and wait for Trigger (CSL offset register is not switched independent of bit CSL_BMOD)
- Set error flag RSTA_EIF when a Restart Request occurs before one of the following conditions was reached:
* The "End Of List" command type has been executed
* Depending on bit STR_SEQA if the "End Of List" command type is about to be executed
* The current CSL has been aborted or is about to be aborted due to a Sequence Abort Request.

– *Requested by:*
- Positive edge of internal interface signal Restart
- Write Access via data bus to set control bit RSTA

10.9.5 List Usage — CSL double buffer mode and RVL double buffer mode

In this use case both list types are configured for double buffer mode (CSL_BMOD=1’b1) and RVL_BMOD=1’b1).

This setup is the same as Section 10.9.3, “List Usage — CSL double buffer mode and RVL double buffer mode but at the end of a CSL the CSL is not always swapped (bit LDOK not always set with bit RSTA). The Result Value List is swapped whenever a CSL is finished or a CSL got aborted.

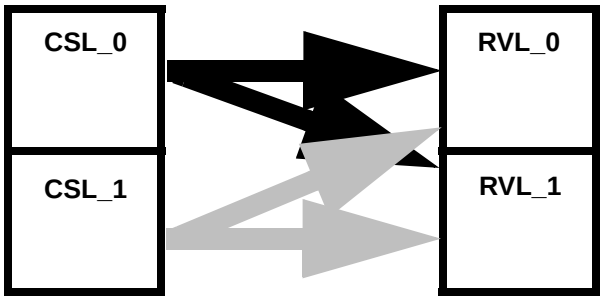


Figure 10-39. CSL Double Buffer Mode — RVL Double Buffer Mode Diagram

10.9.6 RVL swapping in RVL double buffer mode and related registers ADCIMDRI and ADCEOLRI

When using the RVL in double buffer mode, the registers ADCIMDRI and ADCEOLRI can be used by the application software to identify which RVL holds relevant and latest data and which CSL is related to this data. These registers are updated at the setting of one of the CON_IF[15:1] or the EOL_IF interrupt flags. As described in the register description Section 10.5.2.13, “ADC Intermediate Result Information Register (ADCIMDRI) and Section 10.5.2.14, “ADC End Of List Result Information Register (ADCEOLRI), the register ADCIMDRI, for instance, is always updated at the occurrence of a CON_IF[15:1] interrupt flag amongst other cases. Also each time the last conversion command of a CSL is finished and the corresponding result is stored, the related EOL_IF flag is set and register ADCEOLRI is updated. Hence application software can pick up conversion results, or groups of results, or an entire result list driven fully by interrupts. A use case example diagram is shown in Figure 10-40.

Chapter 14
Supply Voltage Sensor (BATSV3)

Table 14-1. Revision History Table

Rev. No. (Item No.)	Data	Sections Affected	Substantial Change(s)
V02.00	16 Mar 2011	14.3.2.1 14.4.2.1	- added BVLS[1] to support four voltage level - moved BVHS to register bit 6
V03.00	26 Apr 2011	allBATSV3	- removed Vsense
V03.10	04 Oct 2011	14.4.2.1 and 14.4.2.2	- removed BSESE

14.1 Introduction

The BATS module provides the functionality to measure the voltage of the chip supply pin VSUP.

14.1.1 Features

The VSUP pin can be routed via an internal divider to the internal Analog to Digital Converter. Independent of the routing to the Analog to Digital Converter, it is possible to route this voltage to a comparator to generate a low or a high voltage interrupt to alert the MCU.

14.1.2 Modes of Operation

The BATS module behaves as follows in the system power modes:

1. Run mode

   The activation of the VSUP Level Sense Enable (BSUSE=1) or ADC connection Enable (BSUAE=1) closes the path from VSUP pin through the resistor chain to ground and enables the associated features if selected.

2. Stop mode

   During stop mode operation the path from the VSUP pin through the resistor chain to ground is opened and the low and high voltage sense features are disabled.
   The content of the configuration register is unchanged.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0009 TCTL2	R	RESERVED	RESERVED	RESERVED	RESERVED	OM1	OL1	OM0	OL0
	W								
0x000A TCTL3	R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED
	W								
0x000B TCTL4	R	RESERVED	RESERVED	RESERVED	RESERVED	EDG1B	EDG1A	EDG0B	EDG0A
	W								
0x000C TIE	R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	C1I	C0I
	W								
0x000D TSCR2	R	TOI	0	0	0	RESERVED	PR2	PR1	PR0
	W								
0x000E TFLG1	R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	C1F	C0F
	W								
0x000F TFLG2	R	TOF	0	0	0	0	0	0	0
	W								
0x0010–0x001F TCxH–TCxL[1]	R	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8
	W								
	R	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	W								
0x0024–0x002B Reserved	R								
	W								
0x002C OCPD	R	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	OCPD1	OCPD0
	W								
0x002D Reserved	R								
0x002E PTPSR	R	PTPS7	PTPS6	PTPS5	PTPS4	PTPS3	PTPS2	PTPS1	PTPS0
	W								
0x002F Reserved	R								
	W								

Figure 16-3. TIM16B2CV3 Register Summary (Sheet 2 of 2)

[1] The register is available only if corresponding channel exists.

16.3.2.1 Timer Input Capture/Output Compare Select (TIOS)

Module Base + 0x0000

	7	6	5	4	3	2	1	0
R W	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	RESERVED	IOS1	IOS0
Reset	0	0	0	0	0	0	0	0

Figure 16-4. Timer Input Capture/Output Compare Select (TIOS)

Read: Anytime

Write: Anytime

When the third edge occurs, the value previously latched from the serial data input pin is shifted into the LSB or MSB of the SPI shift register, depending on LSBFE bit. After this edge, the next bit of the master data is coupled out of the serial data output pin of the master to the serial input pin on the slave.

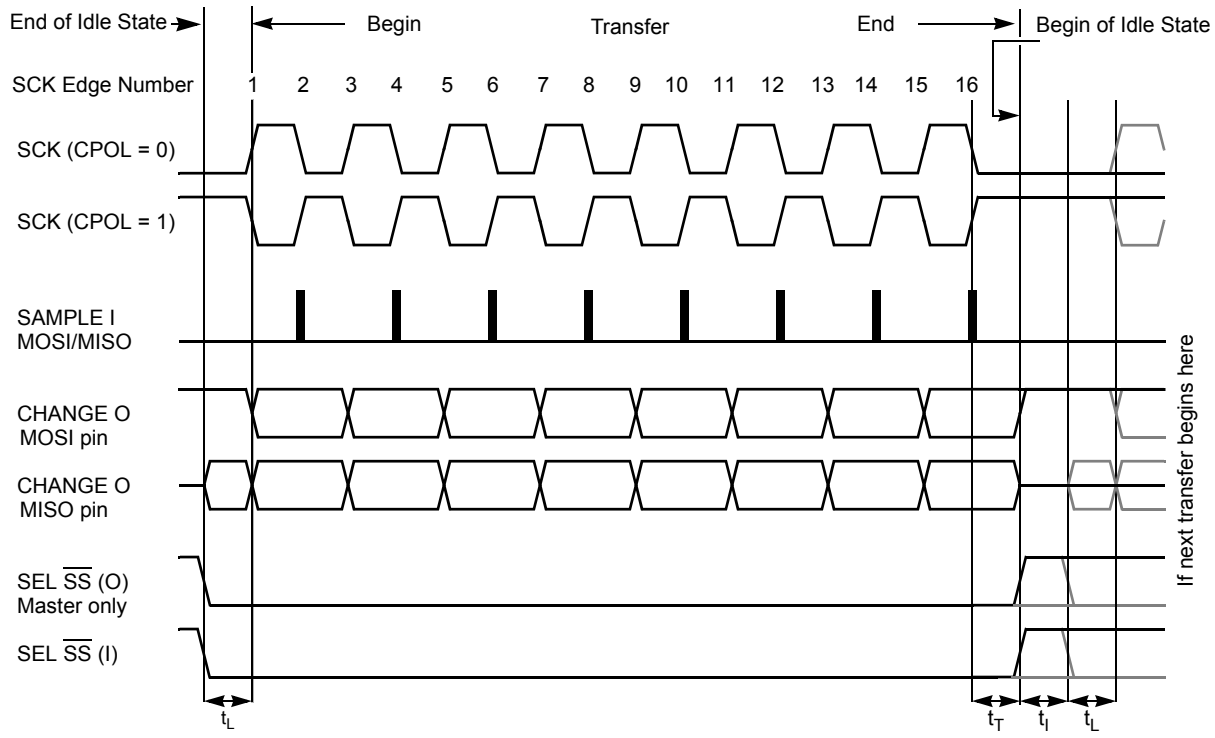
This process continues for a total of n^1 edges on the SCK line with data being latched on even numbered edges and shifting taking place on odd numbered edges.

Data reception is double buffered, data is serially shifted into the SPI shift register during the transfer and is transferred to the parallel SPI data register after the last bit is shifted in.

After $2n^1$ SCK edges:

- Data that was previously in the SPI data register of the master is now in the data register of the slave, and data that was in the data register of the slave is in the master.
- The SPIF flag bit in SPISR is set indicating that the transfer is complete.

Figure 19-14 shows two clocking variations for CPHA = 1. The diagram may be interpreted as a master or slave timing diagram because the SCK, MISO, and MOSI pins are connected directly between the master and the slave. The MISO signal is the output from the slave, and the MOSI signal is the output from the master. The $\overline{SS}$ line is the slave select input to the slave. The $\overline{SS}$ pin of the master must be either high or reconfigured as a general-purpose output not affecting the SPI.



t_L = Minimum leading time before the first SCK edge, not required for back-to-back transfers
t_T = Minimum trailing time after the last SCK edge
t_I = Minimum idling time between transfers (minimum $\overline{SS}$ high time), not required for back-to-back transfers

Figure 19-14. SPI Clock Format 1 (CPHA = 1), with 8-Bit Transfer Width selected (XFRW = 0)

20.2.2 IIC_SDA — Serial Data Line Pin

This is the bidirectional serial data line (SDA) of the module, compatible to the IIC bus specification.

20.3 Memory Map and Register Definition

This section provides a detailed description of all memory and registers for the IIC module.

20.3.1 Register Descriptions

This section consists of register descriptions in address order. Each description includes a standard register diagram with an associated figure number. Details of register bit and field function follow the register diagrams, in bit order.

Register Name		Bit 7	6	5	4	3	2	1	Bit 0
0x0000 IBAD	R	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2	ADR1	0
	W								
0x0001 IBFD	R	IBC7	IBC6	IBC5	IBC4	IBC3	IBC2	IBC1	IBC0
	W								
0x0002 IBCR	R	IBEN	IBIE	MS/$\overline{SL}$	Tx/$\overline{Rx}$	TXAK	0	0	IBSWAI
	W						RSTA		
0x0003 IBSR	R	TCF	IAAS	IBB	IBAL	0	SRW	IBIF	RXAK
	W								
0x0004 IBDR	R	D7	D6	D5	D4	D3	D2	D1	D0
	W								
0x0005 IBCR2	R	GCEN	ADTYPE	0	0	0	ADR10	ADR9	ADR8
	W								

= Unimplemented or Reserved

Figure 20-2. IIC Register Summary

20.4.1.8 Handshaking

The clock synchronization mechanism can be used as a handshake in data transfer. Slave devices may hold the SCL low after completion of one byte transfer (9 bits). In such case, it halts the bus clock and forces the master clock into wait states until the slave releases the SCL line.

20.4.1.9 Clock Stretching

The clock synchronization mechanism can be used by slaves to slow down the bit rate of a transfer. After the master has driven SCL low the slave can drive SCL low for the required period and then release it.If the slave SCL low period is greater than the master SCL low period then the resulting SCL bus signal low period is stretched.

20.4.1.10 Ten-bit Address

A ten-bit address is indicated if the first 5 bits of the first address byte are 0x11110. The following rules apply to the first address byte.

SLAVE ADDRESS	R/W BIT	DESCRIPTION
0000000	0	General call address
0000010	x	Reserved for different bus format
0000011	x	Reserved for future purposes
11111XX	x	Reserved for future purposes
11110XX	x	10-bit slave addressing

Figure 20-13. Definition of bits in the first byte.

The address type is identified by ADTYPE. When ADTYPE is 0, 7-bit address is applied. Reversely, the address is 10-bit address.Generally, there are two cases of 10-bit address.See the Figure 20-14 and Figure 20-15.

S	Slave Add1st 7bits 11110+ADR10+ADR9	R/W 0	A1	Slave Add 2nd byte ADR[8:1]	A2	Data	A3

Figure 20-14. A master-transmitter addresses a slave-receiver with a 10-bit address

S	Slave Add1st 7bits 11110+ADR10+ADR9	R/W 0	A1	Slave Add 2nd byte ADR[8:1]	A2	Sr	Slave Add 1st 7bits 11110+ADR10+ADR9	R/W 1	A3	Data	A4

Figure 20-15. A master-receiver addresses a slave-transmitter with a 10-bit address.

In the Figure 20-15, the first two bytes are the similar to Figure 20-14. After the repeated START(Sr),the first slave address is transmitted again, but the R/W is 1, meaning that the slave is acted as a transmitter.

20.7.1.7 Arbitration Lost

If several masters try to engage the bus simultaneously, only one master wins and the others lose arbitration. The devices which lost arbitration are immediately switched to slave receive mode by the hardware. Their data output to the SDA line is stopped, but SCL continues to be generated until the end of the byte during which arbitration was lost. An interrupt occurs at the falling edge of the ninth clock of this transfer with IBAL=1 and MS/SL=0. If one master attempts to start transmission while the bus is being engaged by another master, the hardware will inhibit the transmission; switch the MS/SL bit from 1 to 0 without generating STOP condition; generate an interrupt to CPU and set the IBAL to indicate that the attempt to engage the bus is failed. When considering these cases, the slave service routine should test the IBAL first and the software should clear the IBAL bit if it is set.

CAUTION

Writing to the Flash registers while a Flash command is executing (that is indicated when the value of flag CCIF reads as ’0’) is not allowed. If such action is attempted, the result of the write operation will be unpredictable.

Writing to the Flash registers is allowed when the Flash is not busy executing commands (CCIF = 1) and during initialization right after reset, despite the value of flag CCIF in that case (refer to Section 22.6 for a complete description of the reset sequence).

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Table 22-2. FTMRZ Memory Map

Global Address (in Bytes)	Description
0x0_0000 – 0x0_0FFF	Register Space
0x10_0000 – 0x1F_4000	EEPROM memory range. Allocation is device dependent.
0x1F_4000 – 0x1F_FFFF	NVM Resource Area[1] (see Figure 22-3)
0x80_0000 – 0xFD_FFFF	P-Flash memory range (Hardblock 0S). Allocation is device dependent.
0xFE_0000 – 0xFF_FFFF	P-Flash memory range (Hardblock 0N). Allocation is device dependent.

[1] See NVM Resource area description in Section 22.4.4

22.3.1 Module Memory Map

The P-Flash memory is located between global addresses 0x80_0000 and 0xFF_FFFF. The P-Flash is high aligned from 0xFF_FFFF. Thus, for example, a 128 KB P-Flash extends from 0xFF_FFFF to 0xFE_0000.

The flash configuration field is mapped to the same addresses independent of the P-Flash memory size, as shown in Figure 22-2.

The FPROT register, described in Section 22.3.2.9, can be set to protect regions in the Flash memory from accidental program or erase. Three separate memory regions, one growing upward from global address 0xFF_8000 in the Flash memory (called the lower region), one growing downward from global address 0xFF_FFFF in the Flash memory (called the higher region), and the remaining addresses in the Flash memory, can be activated for protection. The Flash memory addresses covered by these protectable regions are shown in the P-Flash memory map. The higher address region is mainly targeted to hold the boot loader code since it covers the vector space. Default protection settings as well as security information that allows the MCU to restrict access to the Flash module are stored in the Flash configuration field as described in Table 22-3.

Appendix K
SPI Electrical Specifications

This section provides electrical parametrics and ratings for the SPI.

In Figure K-1 the measurement conditions are listed.

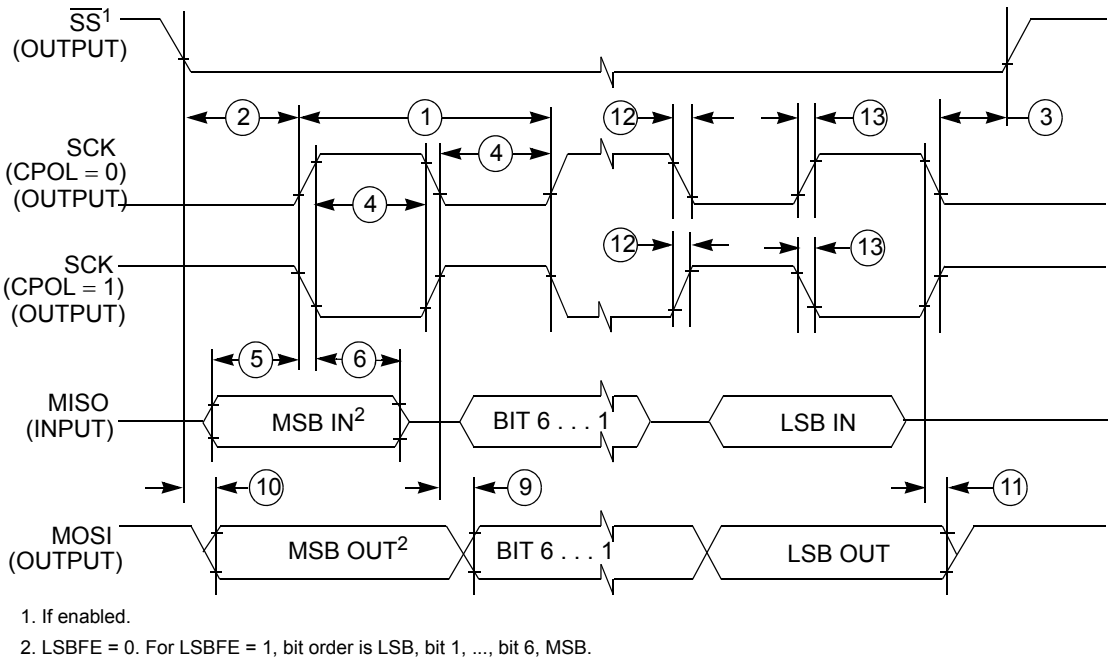
Table K-1. Measurement Conditions

Description	Value	Unit
Drive mode	full drive mode	—
Load capacitance C_{LOAD}[1], on all outputs	50	pF
Thresholds for delay measurement points	(35% / 65%) V_{DDX}	V

[1]Timing specified for equal load on all SPI output pins. Avoid asymmetric load.

K.1 Master Mode

In Figure K-1 the timing diagram for master mode with transmission format CPHA=0 is depicted.



1. If enabled.
2. LSBFE = 0. For LSBFE = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure K-1. SPI Master Timing (CPHA=0)

In Figure K-2 the timing diagram for master mode with transmission format CPHA=1 is depicted.

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE AB IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS T, U, AND Z TO BE DETERMINED AT DATUM PLANE AB.
5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE AC.
6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE AB.
7. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.350.
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

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TITLE: LQFP, 48 LEAD, 0.50 PITCH (7.0 X 7.0 X 1.4)	DOCUMENT NO: 98ASH00962A	REV: G
	CASE NUMBER: 932-03	14 APR 2005
	STANDARD: JEDEC MS-026-BBC	